

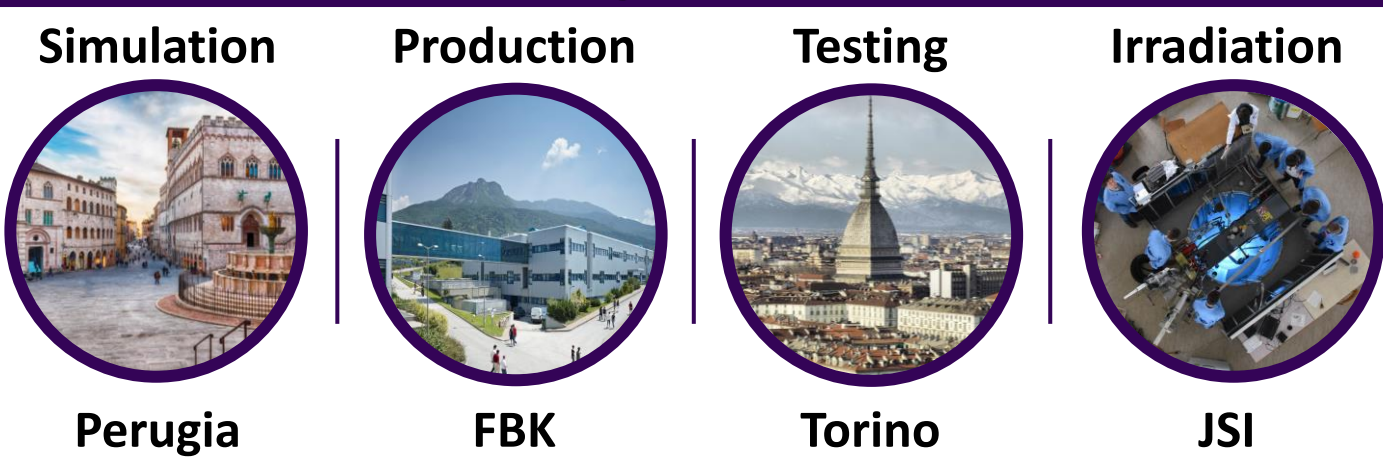
Characterisation of EXFLU1 thin sensors with gain at high fluence

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1) EXFLU1 LGAD sensors

- Developing **radiation-resilient low-gain APDs** to operate in environments of up to $10^{17} \text{ n}_{\text{eq}}\text{cm}^{-2}$
- Planar p-type bulk of thickness 45, 30, 20, and 15 μm , with a 1 μm -thick p⁺ (B, Ga) **gain implant**
- Sensors to feature in the next generation of silicon detectors, e.g. **HL-LHC, FCC**



To characterise these LGAD sensors it is important to understand the gain removal mechanism and how it changes with radiation

2) LGAD design and acceptor removal

Thin sensors measure location and time of a hit simultaneously and accurately

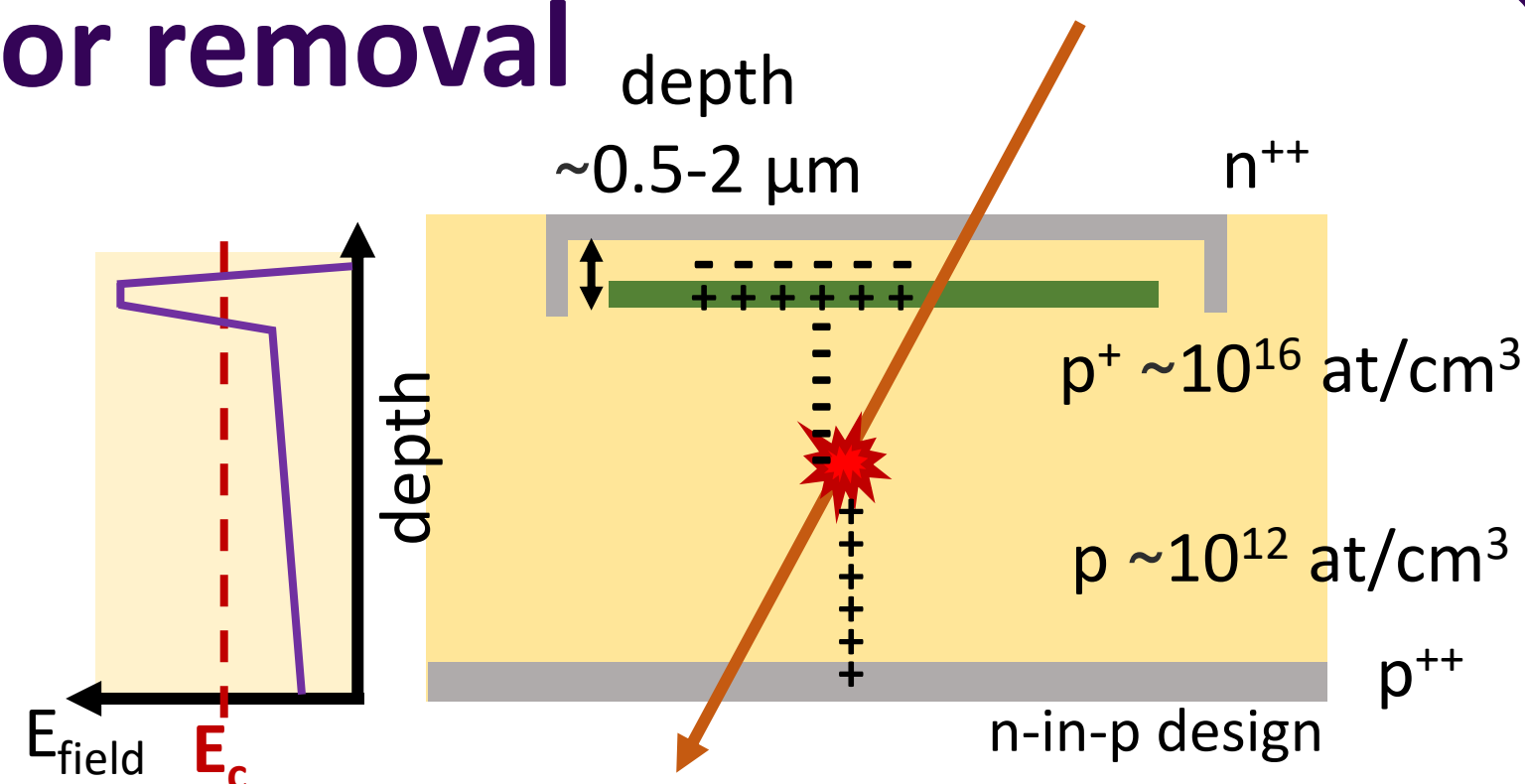
- Spatial and temporal resolution $\sim 30 \text{ ps}$ and $\sim 10 \mu\text{m}$
- Periphery structure tapers E field to mitigate breakdown

LGAD design can withstand $\sim 300 \text{ kV/cm}$ localised to the gain layer

- Gain implant** depletes before bulk and avalanches
- Segmented low-noise, low-leakage **gain $\sim 20-30$**

Acceptor removal deactivates p⁺ doping in gain layer

- Mechanism dependent on **initial acceptor density, p_0^+** , and **defect engineering** in the atomic lattice of the gain implant
- Extract fluence $\Phi = c_A^{-1}$ at which gain contribution is unity



$$p^+(\Phi) = p_0^+ \cdot e^{-c_A \Phi}$$

c_A is the acceptor removal coefficient

3) Methodology

Measurements taken for four sensor thicknesses, before and after irradiation at fluences $\Phi = 1 \times 10^{14}$ to $5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

Thickness / μm	p ⁺ dose	C dose	Diffusion	Bulk
45	1.14	1.0	CBL	n type*
30	1.12	1.0	CBL	high ρ
20	0.96	1.0	CBL	low ρ
15	0.94	1.0	CBL	low ρ

IV characteristics **45 μm substrates are type inverted, where the bulk moves from p type to n type*

- Perform **bias scans** up to depletion at 20, 0, and -20 $^\circ\text{C}$

CV characteristics

- Determine the **depletion voltage** of the gain implant, V_{gl}
- Extract the **rate of degradation**, c_A , in V_{gl} post-irradiation

Gain profile

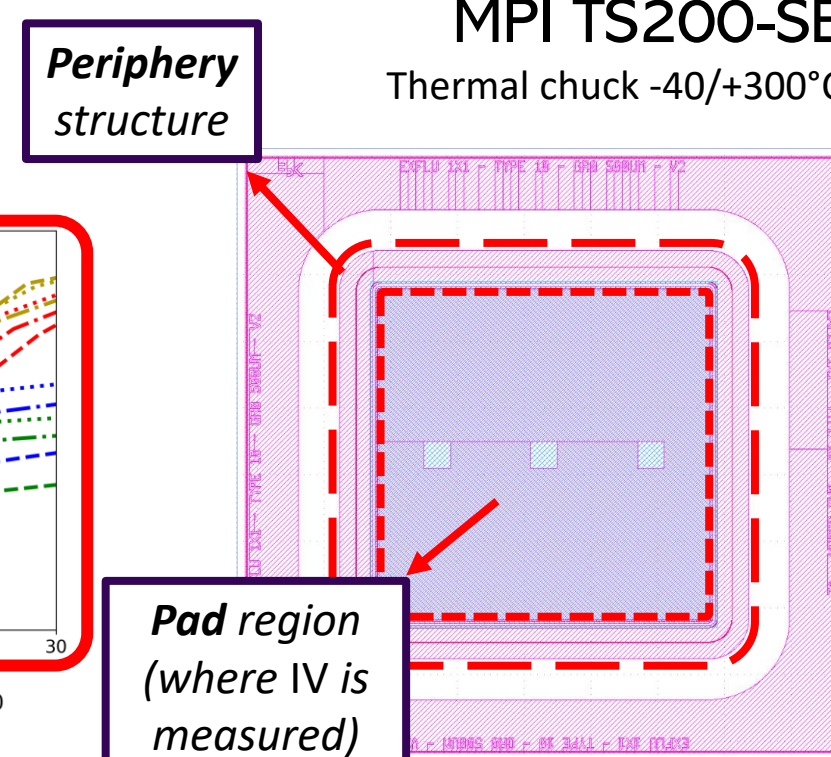
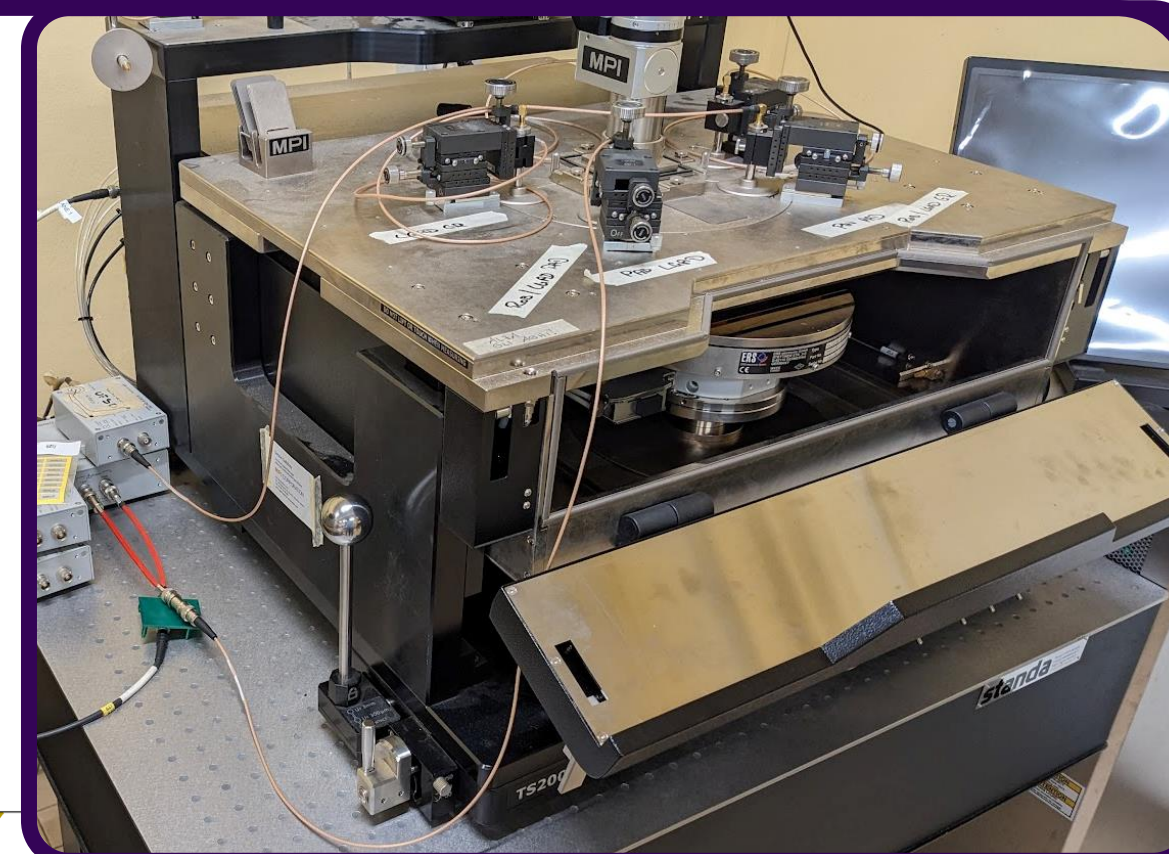
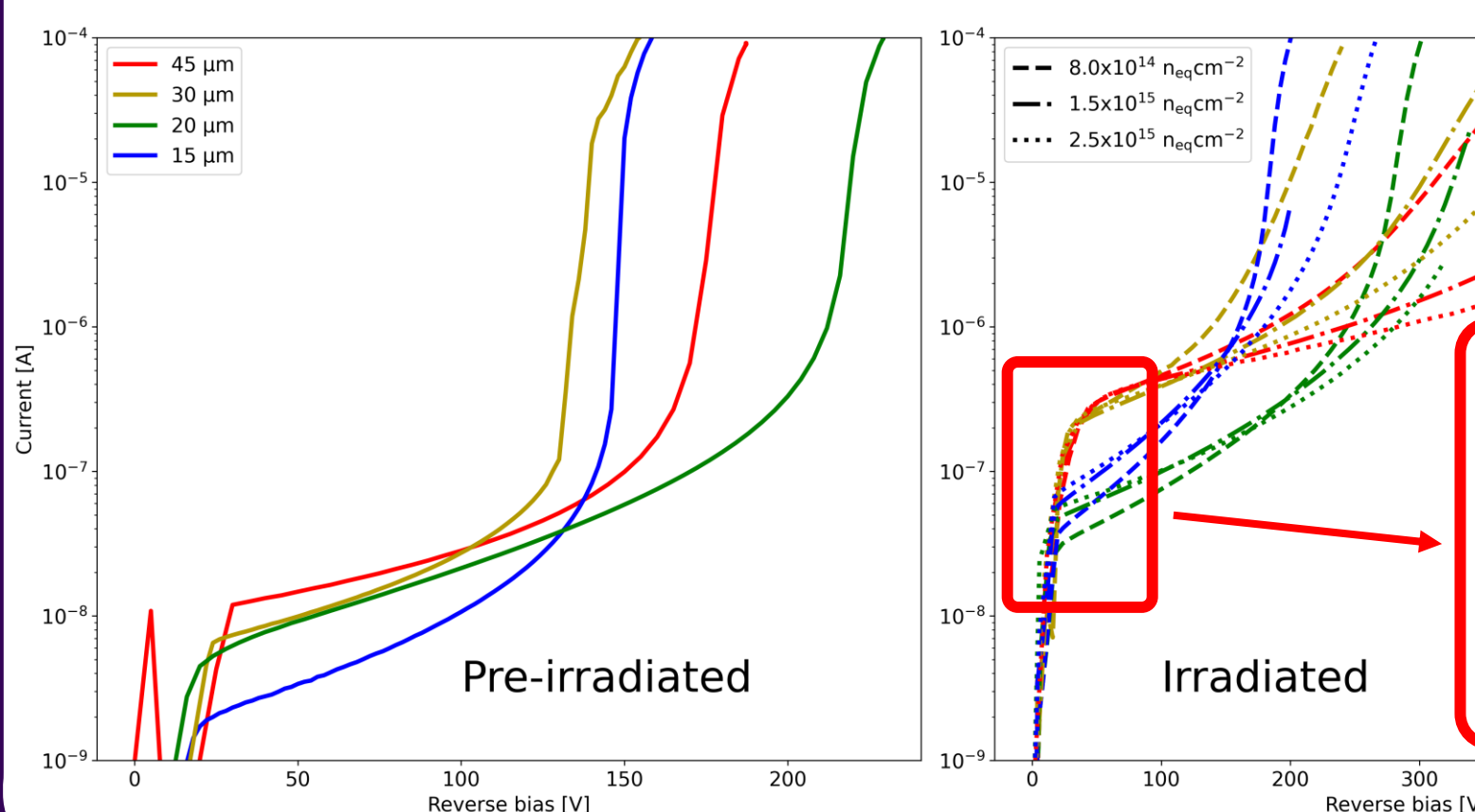
- Extract the contribution due to the gain implant
- Compare the **profiles** for different fluences

4) IV characteristics

Comparison of temperature and irradiation on IV trends

- Gain layer breakdown** visible at low biases $\sim 30 \text{ V}$
- Irradiation** degrades this gain layer breakdown "bump"
- V_{gl} **decreases** as fluence increases (conversely to the bulk)
- Bulk breakdown** trend identical to PIN sensors (not shown)

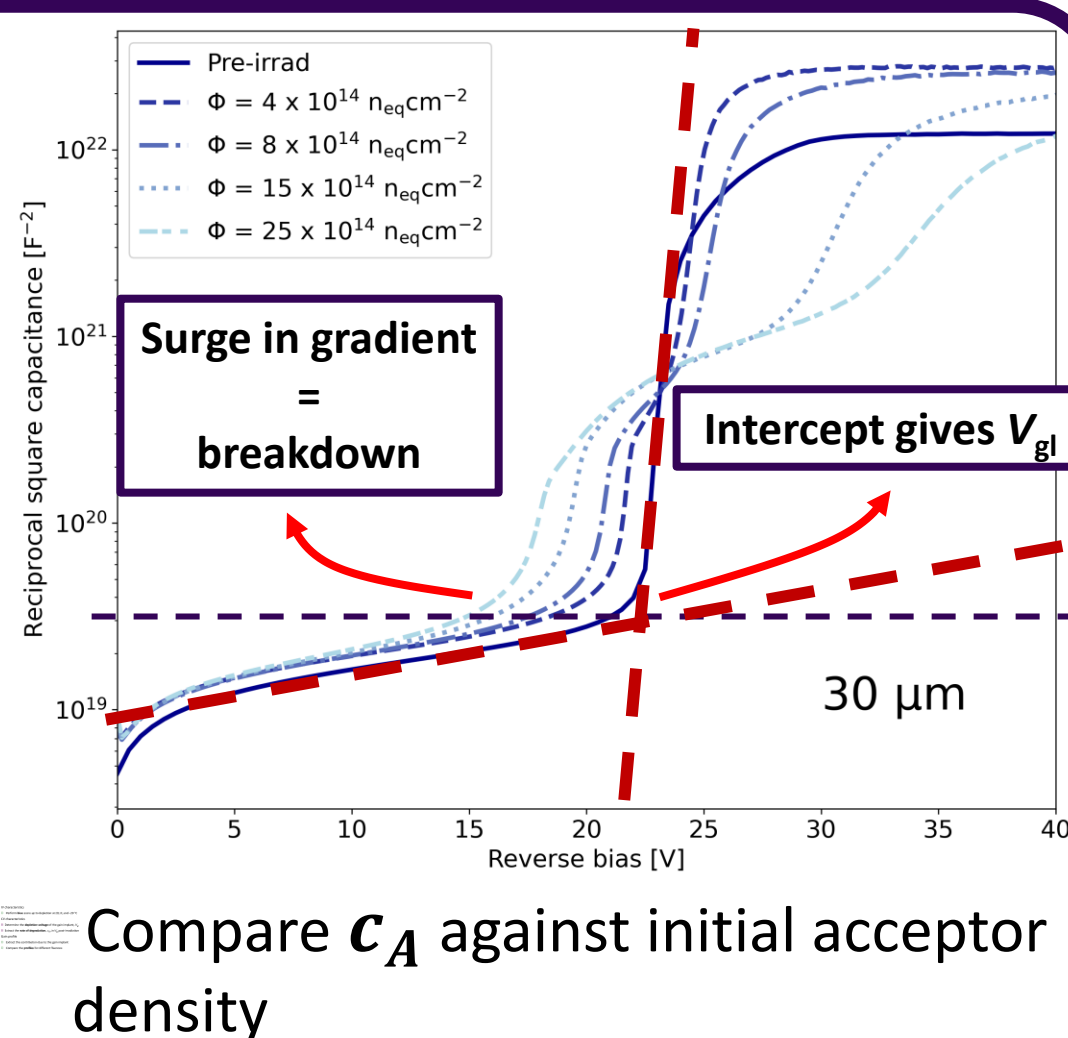
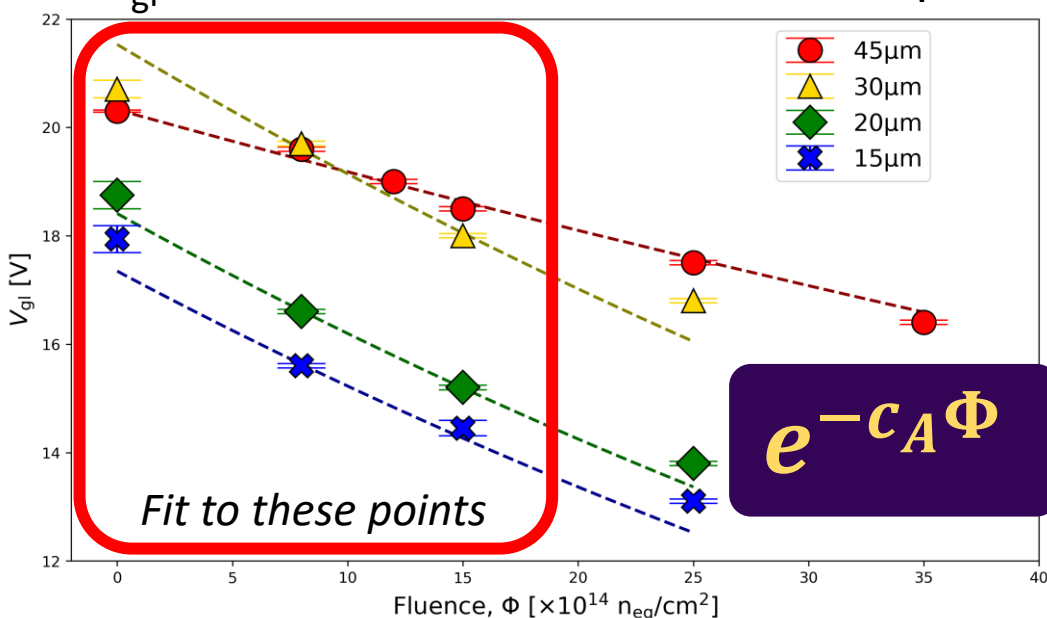
Can study the gain degradation in CV measurements



5) CV characteristics

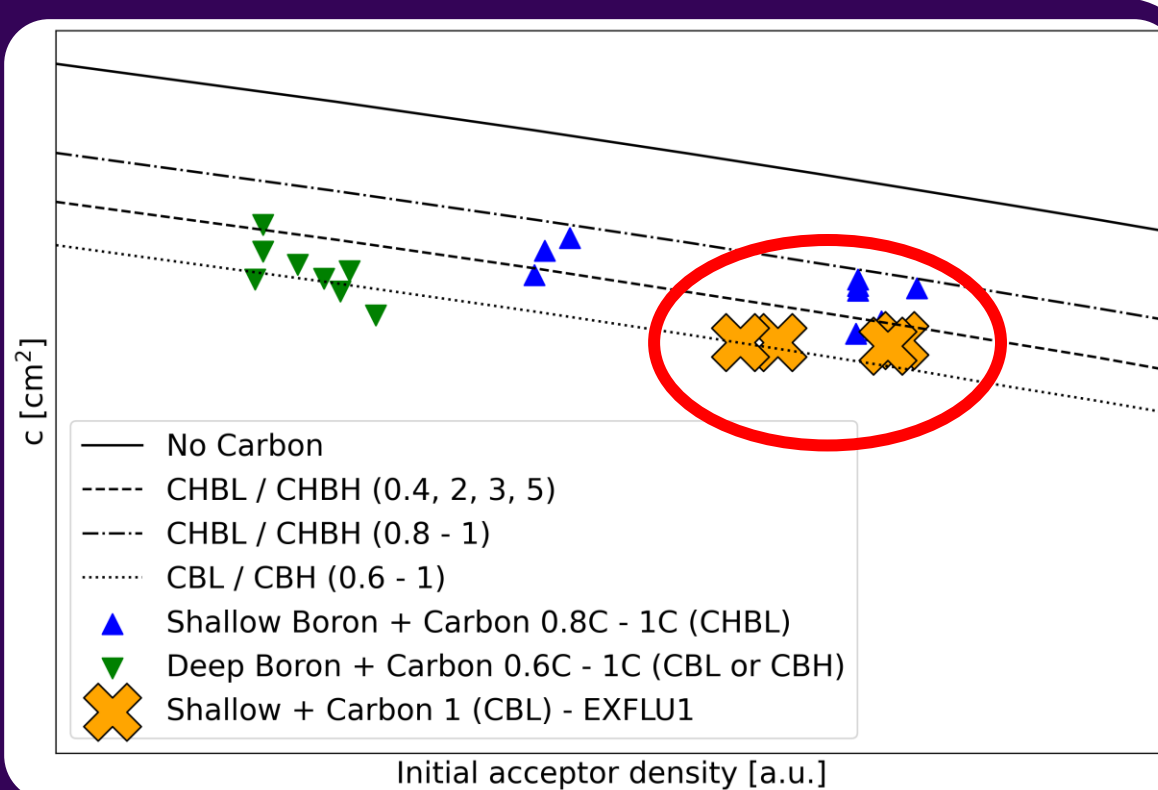
Extract V_{gl} from the C²V curve

- Two linear fits about the breakdown
- V_{gl} is the bias value at their intercept



Best acceptor removal measurements to date!

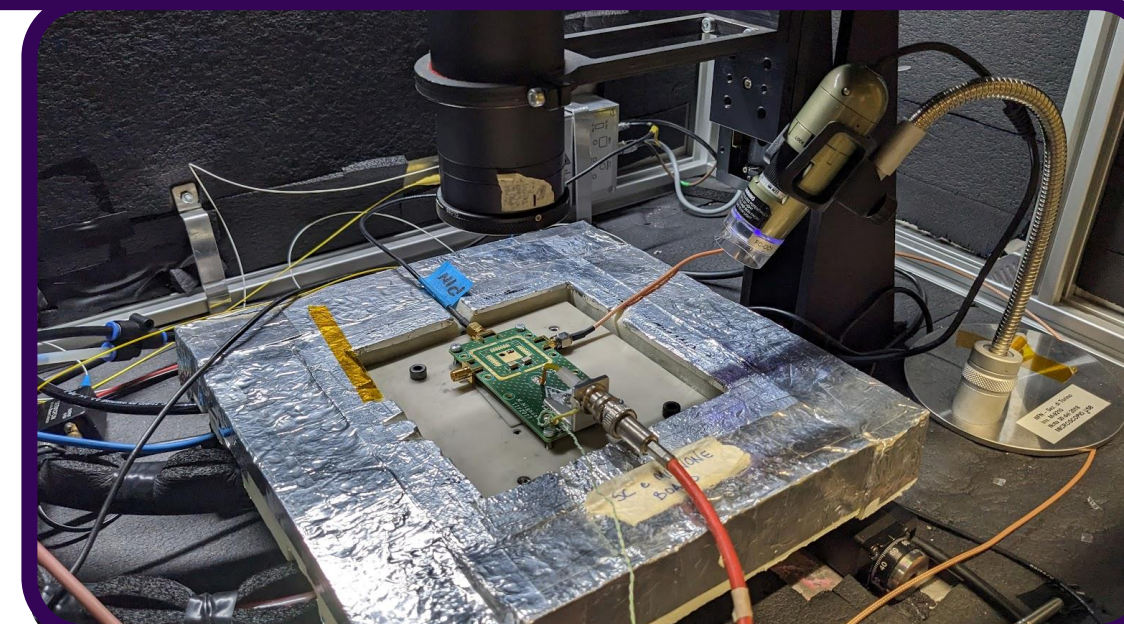
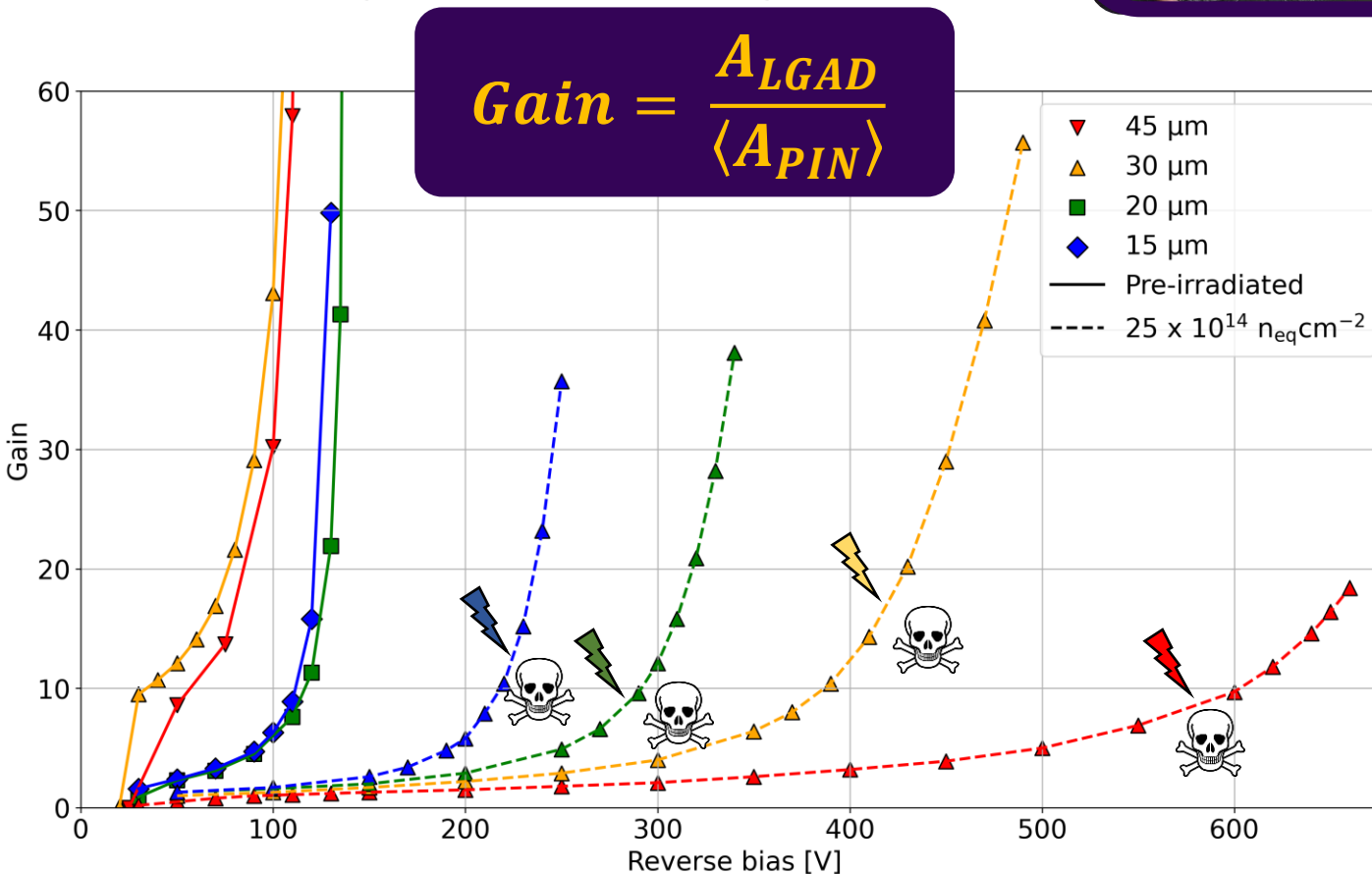
c_A [$\times 10^{-16} \text{ cm}^2 \text{ n}_{\text{eq}}^{-1}$]	Thickness (μm)	Value
45	45	1.39
30	30	1.34
20	20	1.37
15	15	1.37



6) Gain Profile

Gain profile obtained using TCT

- Transient current technique performed inside a black box at -10 $^\circ\text{C}$
- NIR laser at 4 MIPs incident on LGAD-PIN
- Measure signal for increasing bias



Pico-second IR laser at 1064 nm
Laser spot diameter 10 μm
Cividec broadband amplifier (40dB)
Oscilloscope LeCroy 640zi

Gain profiles at pre-irradiation and $\Phi = 2.5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

Single event breakdown limit shown for these results

SEE: 43rd RD50 talk on single event breakdown ref. Marco Ferrero



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